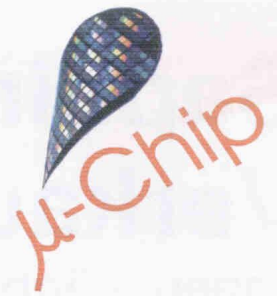


Sapphire Wafers: Sales of Blanks + Job-Shop



Slicing, Lapping, Pre-Polishing

Our Range of Offers

My-Chip Production GmbH offers for sapphire c-a-m-r-axis orientation with/out offset, 2" - 6":

- Slicing, lapping and grinding of sapphire wafers
- Sales of sapphire wafers "as cut"
- Sales of sapphire wafers "as ground"
- Sales of sapphire wafers "pre-polished"
- Sales of substrate wafers, 3" - 6", with/out chamfering and suction holes



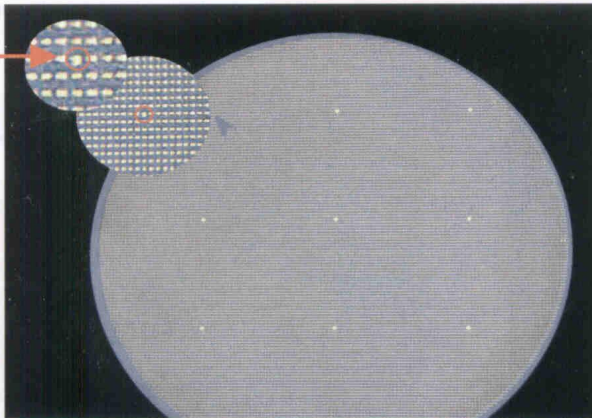
Applications and Advantages

We produce on Logomatic diamond wire saw

Our wafers are used mainly for LEDs productions and as substrate wafers.

- Short cutting time, thus high production capacity (up to 1.000.000 pieces / year)
- High degree of automation, thus competitive to low-salary countries
- Ecologically responsible: because we cut only with diamond wire and city water
- Low cost production possibilities, thus a fair price for You

1 LED
Chip



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my-Chip Production GmbH, Prof.-Hermann-Klare-Str. 6, D - 07407 Rudolstadt, Germany
Tel: +49 (0) 36 72 / 47 82 60, Fax:+49 (0) 36 72 / 47 82 65, , www.german-my-chip.com

Ultrathin Wafers/Chips - Diamond-Multi-Micro-Wire-Saw
Sales of Machines - Development of Technologies - Job-Shop
Silicon, Sapphire, Glass, Quartz, Magnets, Other Brittle Crystals and Materials